A 14-bit 250kS/s Two-step Inverter-based Incremental $\Sigma\Delta$ ADC for CMOS Image Sensor in 0.18 μ m technology

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Abstract This paper presents a 14-bit Incremental Sigma Delta analog-to-digital converter suitable for column wise integration in a CMOS image sensor. A two step conversion is performed to improve the conversion speed. As the same $\Sigma\Delta$ modulator is used for both steps, the overall complexity is reduced. Furthermore, the use of inverter-based amplifiers instead of operational transconductance amplifier facilitates the integration within the column pitch and decreases power consumption. MonteCarlo simulations have been done in order to validate the design of the inverter. The proposed ADC is designed in 0.18 μ m CMOS technology. The simulation is performed with a 1.8 V voltage supply, a 20 MHz system clock frequency and an oversampling ratio (OSR) of 70, and achieves a power consumption is 460 μ W, a SNDR of 85.4 dB at a sampling rate of 250kS/s.

Keywords ADC · incremental · sigma-delta · CMOS Image Sensor · column-parallel · inverter-based

1 Introduction

High quality CMOS imaging sensor (CIS) arrays are reaching performance levels close to scientific CCD arrays. Frame rate and pixel pitch have increased, while read-out noise level has quickly dropped. These developments are considerably raising the requirements on the analog-to-digital converter (ADC) necessarily present in the image processing chain. Several improvements have been tried and developments in this field have arguably converged to column parallel ADC converter arrays, because this configuration has been shown to yield the best tradeoff among pitch, conversion rate, conversion resolution and power consumption.

Fitting the ADC in the ever narrower pixel pitch has driven the converter architectures from straightforward cyc-

lic towards successive approximation register and single slope converters. The latter converters are widely used because of their simplicity and low power consumption. However, they are slow, and achieving more than 10-bit resolution is quite difficult. To raise the resolution above this, the trend is to move towards hybrid converters, where two kinds of converters work in tandem.

Conceptually, the conversion is done in two steps: first the most significant bits (MSBs) are extracted generating an analog residue. In the second step, this residue is converted by the second stage and the least significant bits (LSBs) are obtained. In the Nyquist converters, the analog residue in intermediate steps is proportional to the original analog input. In oversampling converters, such as Sigma-Delta ($\Sigma\Delta$) ADCs, the residue at every step is proportional to the integral of an error signal. In imaging sensor applications, incremental $\Sigma\Delta$ (ISD) ADCs are classically used, where the integrators are reset before each conversion. ISD converters are able to achieve very high resolution while using simple circuits that can be easily scaled down.

For example, Seo et al.[9] have developed a 17-bit $I\Sigma\Delta$ + cyclic ADC, and Shin et al. [10] introduced a 14.3-bits IΣΔ+SAR ADC, both focusing imaging systems. However, these architectures still require moderately complex circuitry due to the use of Nyquist converters in one of the steps. The works reported in Oike et al.[8] and Chen et al.[3] have pushed the concept further by using $I\Sigma\Delta$ ADCs for both steps. The overall OSR is then decreased compared to a standard I $\Sigma\Delta$ ADC and the implementation of the hybrid ADC takes less area and power. A further improvement of IΣ Δ ADCs was the use of inverters to implement the integrators of the $\Sigma\Delta$ loop, as reported by Chae *et al.*[2], as well as Wang et al.[13] and Tang et al.[12]. However, ensuring a high DC gain over an appreciable output voltage range is a challenging task. Still, the key advantage of inverter-based IΣ Δ ADC is the reduction in area and power consumption.

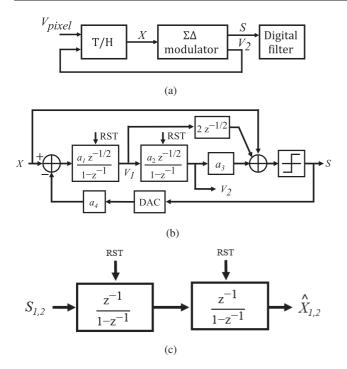


Fig. 1 (a) High-level view of two-steps architecture, schematic of the track and hold, (b) $I\Sigma\Delta$ second order modulator with feed-forward and (c) schematic of the digital filter of the ADC

In this paper, a 14-bit two-step inverter-based IS Δ using a second-order cascaded integrators feed-forward (CIFF) is introduced. The main contribution of our proposal is the reuse of a second-order modulator for both steps, in addition to the use of gain-boosted inverter-based integrators. With the use on double-sided ADCs above and below pixel array, the required ADC width can be twice the pitch of the pixel, so up to 25 μ m in a space imaging application. The important specifications set on this ADC are the resolution and the sampling frequency. This sampling frequency, which is the ADC frequency conversion, must be at least 220 kS/s with a resolution of 14-bit for a full HD image sensor working at 100 FPS. No requirements have been set at that moment on the power dissipation and the length of the ADC.

This paper is organized as follows; In section 2, the high-level IS Δ architecture is presented. In section 3, the circuit implementation of the ADC is shown. In section 4, results from simulations are shown and compared to similar work. Section 5 concludes this paper.

2 Proposed two-step ADC architecture

2.1 Two-step theory

The high-level view of the proposed ADC architecture is shown in fig.1(a). The architecture is composed with a track and hold (T/H), a $\Sigma\Delta$ modulator and a digital filter. The

chosen modulator is a second-order CIFF architecture [6] shown in fig.1(b).

Our two-step I $\Sigma\Delta$ ADC first performs a coarse conversion of the pixel value stored in the T/H, giving an analog residue V_2 loaded into the T/H. Then a fine conversion is performed on this residue, using the same modulator. The residue of the coarse conversion can be expressed as follows

$$V_2[M1] = a_1 a_2 \sum_{K=1}^{M_1 - 1} \sum_{i=1}^{K-1} (X[i] - a_4 S_1[i])$$
 (1)

with a_1 and a_2 coefficients in the modulator, M_1 the number of samples for the first step, X the input signal stored and held by the T/H at the start of the conversion and S_1 the bitstream of the coarse conversion. The fine conversion is then performed on this residue. The final reconstructed signal is then a linear combination of both bitstreams and can be written as

$$\hat{X} = K_1 \sum_{K=1}^{M_1 - 1} \sum_{i=1}^{K - 1} S_1[i] + \frac{K_1 K_2}{a_1 a_2} \sum_{K=1}^{M_2 - 1} \sum_{i=1}^{K - 1} S_2[i]$$
 (2)

with

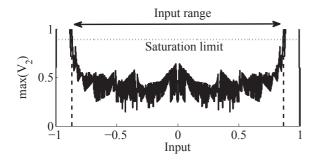
$$K_i = \frac{2}{(M_i - 1)(M_i - 2)} \tag{3}$$

where i=1,2, M_2 is the number of samples for the second step, S_2 the bitstream of the fine conversion and K_i the coefficient associated with the coarse and fine conversion. To maximize the resolution, M_1 and M_2 must be equal[1]. We take $M_1 = M_2 = 35$ to reach the aimed resolution. So, a clock frequency $f_c l k$ =20Mhz is enough to achieve a sampling rate 220kS/s.

2.2 Modulator scaling

In a two-step ADC the difference between the output of the first step of the conversion $(V_2[M_1])$ and the effective input of the second step can highly deteriorate the overall resolution. To optimize this range difference, the I $\Sigma\Delta$ must be analyzed in the time domain instead of the frequency domain.

One can see from (1) that the residue depends on the modulator coefficients a_1 , a_2 and a_4 . They must be adjusted to maximize the residue range within the input range. This optimization must also guarantee a non-saturation of the amplifiers and a tolerance to possible offsets. For this design, the amplifier input range is limited to 85% of the reference scale and integrators levels do not go above 90% of the reference. The parameters a_1 , a_2 , a_3 , a_4 were optimized by simulation and their values are respectively 0.5, 0.5, 0.75 and 0.5. With this set of parameters, the simulation of the maximum integrator value and the residue value are respectively shown in fig.2. In both results, values do not exceed the saturation or output limit for any input. The residue range is



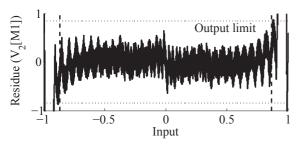


Fig. 2 Maximum of second integrator level (top) and residue values (bottom) with both axis scaled to $\Sigma\Delta$ reference level

about 75% of the input range of the modulator. Since the saturation of the amplifier is avoided and the residue range fits the input range of this modulator, this architecture is suitable for a two-step ADC.

As one can see in the eq.(2), coefficients a_1 and a_2 appear in the reconstruction formula of input signal. In the next calculation, we do not consider the gain of the S/H, but the method remains the same. The circuit being implemented with a switched-capacitors (SC) circuit, the effective value of these coefficients depends of the technology mismatches. Using (2), one can find for the input signal X the exact equation of the input converter is

$$X = K_1 \sum_{K=1}^{M_1 - 1} \sum_{i=1}^{K - 1} S_1[i] + \frac{K_1 K_2}{a_{1R} a_{2R}} \sum_{K=1}^{M_2 - 1} \sum_{i=1}^{K - 1} S_2[i] + \frac{K_1 K_2}{(a_{1R} a_{2R})^2} V_2[M_2]$$

$$(4)$$

where a_{1R} and a_{2R} represent the real coefficients in the analog modulator. The last term, proportional to the residue of the second step, therefore provides the accuracy of the ideal ADC. Now one can look at the difference between X and \hat{X} , E_{RR} , from the (2) and (4) and can be expressed as

$$E_{RR} = \left[K_1 K_2 \sum_{K=1}^{M_2 - 1} \sum_{i=1}^{K - 1} S_2[i] \right] \left[\frac{1}{a_1 a_2} - \frac{1}{a_{1R} a_{2R}} \right] - \frac{K_1 K_2}{(a_{1R} a_{2R})^2} V_2[M_2]$$
(5)

The error at the end of the conversion is composed with a term depending on the last residue $V_2[M_2]$ and with a term due to the mismatch of the coefficients a_1 and a_2 . These values in the switched capacitor filter must be known precisely,

otherwise an extra calibration is needed to reach the full resolution. The variation of these coefficients can be reduced in its implementation with a suitable capacitance matching by using only unitary capacitance values.

2.3 Digital Filter

As a reset occurs at each conversion, the digital filter of the $I\Sigma\Delta$ is different from the classic $\Sigma\Delta$. For a two-step $I\Sigma\Delta$ with feed-forward in the modulator, in order to recover the input signal from the bitstream, the digital filter is similar to the discrete time filter as a dual integrator. The digital filter is shown in the fig.1(c). The ADC being an $I\Sigma\Delta$, a reset is also done on the digital filter at the beginning of each conversion. A weighted summation of the integrated values for each step is then performed. Multipliers must be added to perform this weighting operation.

3 Circuit implementation

The T/H and the switched capacitor schematics of the modulator are shown in fig.3(a) and fig.4 respectively. In both circuits, amplifiers have been designed with CMOS inverters to reduce area. For each ratio of capacitance, the capacitance value is a multiple of an unitary capacitance. The unitary value of 150 fF has been chosen by considering the technology (0.18um), the noise kTC and the requirement for the Gain Bandwidth (GBW).

Since inverter amplifiers have very large offset variation due to the process, we use an auto-zeroing scheme proposed in [2] for integrators.

A similar method is applied to the T/H and is shown in fig.3(b). Before the beginning of the coarse conversion, the pixel value is loaded into the capacitance C_{SH} (switches S1

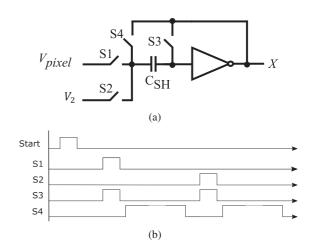


Fig. 3 (a) Schematic of the T/H stage and (b) Timing control of the S/H switches

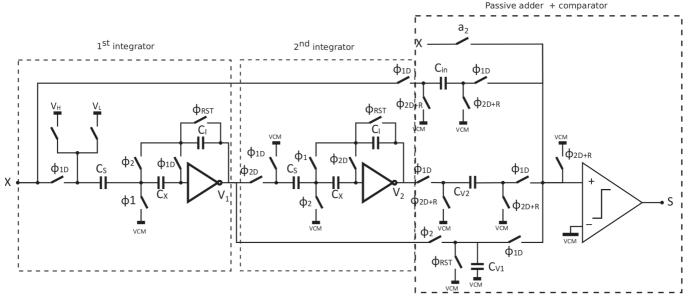


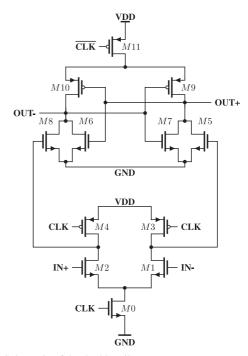
Fig. 4 Switched capacitor implementation of the 2^{nd} order modulator

and S3 closed, S2 and S4 opened). Then the value of the pixel is disconnected from the amplifier (S1 and S3 being open). Then S4 is closed and S3 opened, canceling the offset of the amplifier and storing the pixel value at the end of the operation. To load the residue $V_2[M_1]$ into the T/H at the end of the coarse conversion, the switch sequence is the same except that S2 is closed instead of S1 to select the right input.

3.1 Passive adder and comparator

The remaining circuit block required for the implementation of the modulator is a passive adder filtered by a low-power, fast, clocked comparator [7]. The schematic of this comparator is shown in fig.5. In a ISD ADC, the comparator offset only impacts the input dynamic range of the modulator. The input transistors (M1 and M2) are the most important to define comparator specifications as offset and decision time. To meet our requirements for these specifications, a good compromise is to set the input transistors size to (W/L)= $(4\mu m/1 \mu m)$.

By performing monte carlo simulations on the comparator, one can see in the fig.6 that the value of the offset goes from -12 to 8 mV with a mean value of -2 mV and a standard deviation of 4.5 mV. In order to be fast enough, the comparator must make its decision in less than 3 ns, considering the non-overlapping block. For two inputs values very close, which is the worst case possible in terms of speed, one can see in the fig.6 that the decision time of the comparator is up to 2.5 ns. This value is less than the required speed/offset, validating the comparator architecture.



 $\textbf{Fig. 5} \quad \text{Schematic of the double tail comparator} \\$

3.2 Inverter amplifier

It has been shown [1] that the amplifier gain needed to reach 14-bit resolution with this type of modulator is at least 80 dB. The small signal DC gain of an inverter is expressed as follows

$$A_{\nu} = (g_{m(N)} + g_{m(P)})(r_{o(N)} / / r_{o(P)})$$
(6)

where $g_{m(N)}$ and $g_{m(P)}$ represent the transconductance of NMOS and PMOS respectively, $r_{o(N)}$ and $r_{o(P)}$ their output

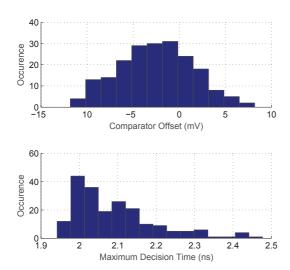


Fig. 6 MonteCarlo simulations of offset and decision time of the schematic comparator

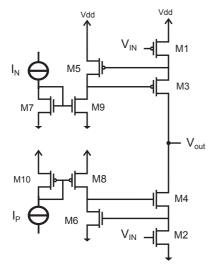


Fig. 7 Gain boosted inverter amplifier

resistance. From eq.(6) one can see that the gain can be increased with $r_{o(N,P)}$. Cascoding is a common way to raise the output resistance. However simple and cascoded inverters cannot reach a sufficiently high gain in this technology. Our solution is to add gain-boosting to the inverter [5]. The schematic of a gain-boosted inverter is shown in fig.7.

Thanks to the gain boosting amplifier circuit, the effective transconductance of the cascode transistor is increased, hence considerably increasing the output resistance of the inverter-based amplifier. A trade-off has to be found between the maximum DC gain and output linearity. To ensure good output linearity swing, low-threshold transistor are used in the gain-boosting module (M5 and M6). Moreover the PMOS transistor are sized larger than the NMOS to improve the

Table 1 Inverter transistors sizes

Transistor	(W/L)
M1	20 μ / 0.36 μ
M2	5 μ / 0.36 μ
M3	30 μ / 0.36 μ
M4	7.5 μ / 0.36 μ
M5	8 μ / 0.36 μ
M6	2 μ / 0.36 μ

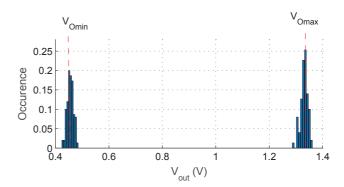


Fig. 8 Montecarlo simulation of the dynamic output range where a DC gain of 80 dB is ensured. V_{Omax} and V_{Omin} are normally distributed around the nominal values

symmetrical output range. The inverter transistors sizes are shown in the table 1.

The inverter can be seen as a current source during the transient phase of the charge transfer, or as a voltage source in DC mode, when all the charges have been transferred. The second case is investigated in this section. The output linearity swing is the output range of the amplifier where a minimum DC gain of 80 dB is ensured [1]. A monte-carlo analysis of the inverter is realized and the output linearity is observed. The gain-boosted inverter amplifiers were sized to achieve a small signal gain of at least 80 dB with symmetrical headroom of around 0.45 V from both supply rails. Monte carlo simulations were then ran to check how far the linear output range would change for the 10 μ m pitch layout. The spread of the upper (V_{Omax}) and the lower (V_{Omin}) are given in the fig.8. The worst case value (0.5-1.3 V) are sufficient for our requirements.

Considering the temperature dependencies of the amplifier over the different corners, the output linearity and the GBW were also obtained by simulations and the results are shown in Table.2. The different cases ws and wp represent respectively the worst speed and the worst power scenario for three different temperatures (25, -20 and 85 °C). One can see that all the cases are good with regard to the linearity and the GBW, except the case "wp85", in which the gain-boosting circuit does not ensure enough feedback. The re-

 ${\bf Table~2~Inverter~amplifier~characteristics~over~different~corner~and~the~temperature}$

Case	V_{Omin}	V_{Omax}	ΔV_O	GBW
	(V)	(V)	(V)	(MHz)
Typical	0.419	1.375	0.96	328
ws25	0.438	1.377	0.94	266
wp25	0.394	1.357	0.96	397
ws-20	0.458	1.361	0.90	228
wp-20	0.388	1.395	1.00	455
ws85	0.438	1.362	0.92	240
wp85	0.451	1.173	0.72	232

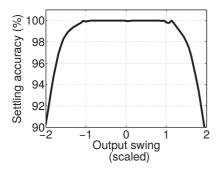


Fig. 9 Settling accuracy of an integration step

maining issue in a low-voltage switched-capacitor circuit is the choice of switches, which influences the settling time of the voltages on the capacitors. With the designed switches, the settling accuracy of a transition from the voltage common mode to the extreme value is shown in fig.9. The X-axis, the output swing, is scaled to the $\Sigma\Delta$ reference. From this figure, one can observe that an accuracy of 99.9% is guaranteed for an output swing of 95% of the IS Δ reference.

4 Results

The proposed two-step inverted based ADC full transistor level was simulated in 0.18 μ m technology. The supply voltage of the circuit is 1.8 V. The static current for a gain-boosting module is about 4 μ W and 140 μ W for an amplifier, with an overall ADC power consumption of 460 μ W. With a main clock f_clk =20 MHz and an overall OSR of 70, the conversion is performed in less than 4 μ s, so its sampling rate is finaly up to 250 kS/s.

4.1 Schematic simulation results

Output spectrum is presented in fig.10 with an input signal frequency of 5 kHz and a 256 points FFT. This work

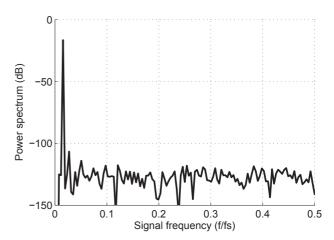


Fig. 10 Simulated output spectrum of ISA ADC with a 256 points FFT

achieves a SNR of 85.4 dB. The figure-of-merit (FoM) is written as follows,

$$FoM = \frac{P}{2^{ENOB}.Fs} \tag{7}$$

with P the power dissipation of the ADC, *ENOB* the effective number of bits calculated from the SNR, and F_s the sampling frequency of the ADC. This ADC achieves a FoM of 150 fJ/step. A comparison with similar works is shown in Table 3. This work consumes lower power and is very competitive compared to previous results. Its layout size is 25 μ m \times 240 μ m and is be suitable for a 12.5 μ m pixel pitch when using double-sided ADC.

4.2 Post-layout simulation results and calibration

Post-layout simulations have been performed before sending the chip to foundry. In this part, results are found by using a ramp at the input of the ADC. As seen in fig.11.top, by applying a 140 points ramp within 75% of the feedback range (thus becoming the input range), a resolution of almost 12bit is achieved. The global performance can be enhanced by performing a calibration and linear digital correction. The correction consists in a multiplicative coefficient for each bit and an offset. The correction coefficients have been determined 'offline' by using the least square method and minimizing the conversion error. The efficiency of the calibration on this ADC and the results are shown in fig.11.bottom. The green dots represents the samples used for the calibration. The red points are extra random samples, not used during the calibration. One can see that the resolution of the ADC almost reaches 14-bit. As this calibration requires as many corrective terms as output cycles (70), a simplification of this calibration and correction will be investigated in a future work.

Table 3 Performance comparison

	[9]	[11]	[4]	[8]	This work
Technology (µm)	0.18	0.35	0.18	0.15	0.18
ADC architecture	ΣΔ+Cyclic	$\Sigma\Delta$ +SAR	ΣΔ+Cyclic	2 step $\Sigma\Delta$	2 step $\Sigma\Delta$
Sampling rate (kS/s)	30	150	50	-	250
Resolution	17	14.3	10.2	12	14
Power (μW)	345	300	13	363	460
DNL (LSB)	-0.88/1.38	-0.79/0.97	-	-0.7/1.8	-
INL (LSB)	-26.3/35	-1.7/2.79	-	-22/20	-
SNDR (dB)	85	-	63	-	85.4
FoM (fJ/step)	790	100	220	-	129

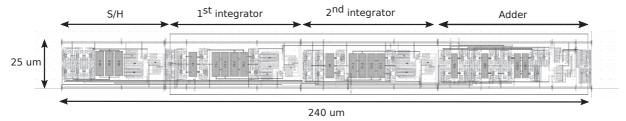


Fig. 12 Layout of the ADC

5 Conclusion

A two-step inverter-based IS Δ ADC was presented in this paper. The $\Sigma\Delta$ modulator was first analyzed. Then the circuit implementation of the T/H and the $\Sigma\Delta$ inverter-based modulator was analyzed. Finally simulations results were presented. This work has shown that hardware reuse can be

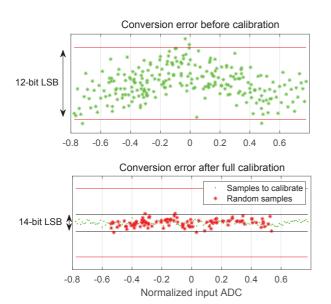


Fig. 11 Calibration of Post-layout simulations

realized for ADC in CMOS image Sensor. This point allows to decrease the overall size of the ADC and this architecture is a good trade-off for medium speed (250 kS/s) and high resolution (14-bit) ADC. We showed that using a supply voltage of 1.8 V, a clock frequency of 20 MHz, a total OSR of 70, this schematic ADC achieves a SNR of 85.4 dB for a power consumption of 460 μ W. After layout, an effective resolution of 12 bits is reached, and could be extended to 14 bits with digital correction. The FoM of the ADC is 129 fJ/step. Future work is to send the chip to foundry and realize a simplified embedded calibration and digital correction for the ADC.

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